

PSMN5R6-100YSF

NextPower 100 V, 6 m Ω N-channel MOSFET in LFPAK56 package

17 August 2018

Preliminary data sheet

1. General description

NextPower 100 V standard level gate drive MOSFET. Qualified to 175 °C and recommended for industrial & consumer applications.

2. Features and benefits

- Low Q_{rr} for higher efficiency and lower spiking
- Qualified to 175 °C
- Low Q_G x R_{DSon} FOM for high efficiency switching applications
- Strong avalanche energy rating (E_{as})
- Avalanche rated and 100% tested
- Ha-free and RoHS compliant LFPAK56 package
- Wave-solderable LFPAK56 package

3. Applications

- · Synchronous rectifier in AC-DC and DC-DC
- · BLDC motor control
- USB-PD and mobile fast-charge adapters
- LED lighting
- · Full-bridge and half-bridge applications
- · Flyback and resonant topologies

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C		-	-	100	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>		-	-	120	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>		-	-	294	W
Tj	junction temperature			-55	-	175	°C
Static charact	eristics					·	·
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; Fig. 12		-	4.5	5.6	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 100 °C; Fig. 13		-	7.3	8.7	mΩ
Dynamic char	acteristics					'	
Q_{GD}	gate-drain charge	I _D = 25 A; V _{DS} = 50 V; V _{GS} = 10 V;		-	13.5	-	nC
Q _{G(tot)}	total gate charge	Fig. 14; Fig. 15		-	65.1	-	nC
Avalanche ruggedness							



Symbol	Parameter	Conditions		Min	Тур	Max	Unit
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	I_D = 41.8 A; $V_{sup} \le 100$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; Fig. 4; Unclamped	[1]	-	-	440	mJ
Source-drain o	liode						
Q _r	recovered charge	$I_S = 25 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}; Fig. 18$		-	67.3	-	nC

^[1] Protected by 100% test

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	ربومها	D
2	S	source		
3	S	source		G (F)
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4 LFPAK56E; Power-	
			SO8 (SOT1023)	

6. Ordering information

Table 3. Ordering information

Type number Package					
	Name	Description	Version		
PSMN5R6-100YSF	LFPAK56E; Power-SO8	plastic, single-ended surface-mounted package (LFPAK56); 4 leads; 1.27 mm pitch	SOT1023		

7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN5R6-100YSF	5F6S10

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	100	V
V_{DGR}	drain-gate voltage	25 °C ≤ T_j ≤ 175 °C; R_{GS} = 20 kΩ	-	100	V
V_{GS}	gate-source voltage		-20	20	V
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	294	W
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	-	120	Α

Symbol	Parameter	Conditions		Min	Max	Unit
		V _{GS} = 10 V; T _{mb} = 100 °C; <u>Fig. 2</u>		-	112	Α
I _{DM}	peak drain current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 °C$; Fig. 3		-	480	Α
T _{stg}	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
T _{sld(M)}	peak soldering temperature			-	260	°C
Source-drain	n diode					
I _S	source current	T _{mb} = 25 °C		-	120	А
I _{SM}	peak source current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 ^{\circ}C$		-	480	Α
Avalanche re	uggedness					
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	I_D = 41.8 A; $V_{sup} \le 100$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; Fig. 4; Unclamped	[1]	-	440	mJ
I _{AS}	non-repetitive avalanche current	$V_{sup} \le 100 \text{ V}; V_{GS} = 10 \text{ V}; T_{j(init)} = 25 \text{ °C}; R_{GS} = 50 \Omega$	[1]	-	41.8	А

[1] Protected by 100% test

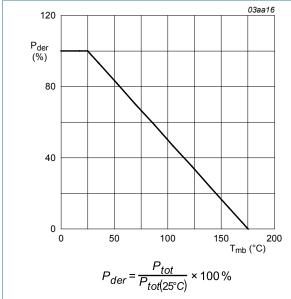


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

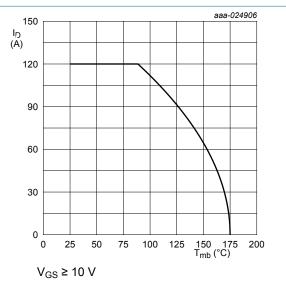
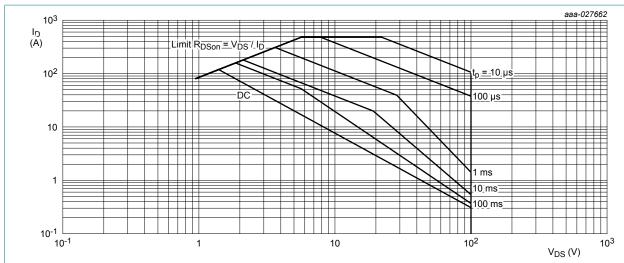
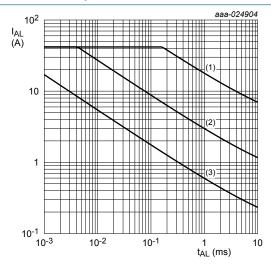


Fig. 2. Continuous drain current as a function of mounting base temperature



 T_{mb} = 25 °C; I_{DM} is a single pulse

Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



(1) $T_{j \text{ (init)}}$ = 25 °C; (2) $T_{j \text{ (init)}}$ = 150 °C; (3) Repetitive Avalanche

Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 5	-	0.45	0.51	K/W
R _{th(j-a)}		Fig. 6	-	42	-	K/W
junction to ambient	Fig. 7	-	85	-	K/W	

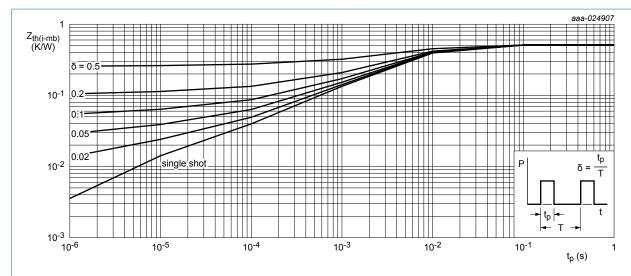
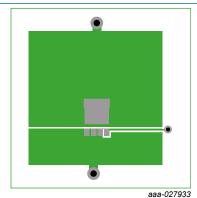
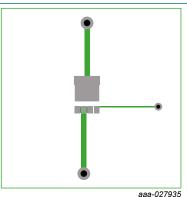


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration



Copper area 25.4 mm square; 70 μ m thick on FR4 board

Fig. 6. PCB layout for thermal resistance from junction to ambient



70 µm thick copper on FR4 board

Fig. 7. PCB layout with minimum footprint for thermal resistance from junction to ambient

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static charac	cteristics					
V _{(BR)DSS}	drain-source	I _D = 250 μA; V _{GS} = 0 V; T _j = 25 °C	100	-	-	V
	breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = -55 °C	90	-	-	V
V _{GS(th)}	gate-source threshold	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-	3.6	-	V
	voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ °C}$	-	1.8	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}; Fig. 11$	2	3.1	4	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	25 °C ≤ T _j ≤ 175 °C	-	-8.8	-	mV/K
I _{DSS}	drain leakage current	$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	0.03	5	μΑ
		V _{DS} = 100 V; V _{GS} = 0 V; T _j = 125 °C	-	-	100	μΑ
I _{GSS}	gate leakage current	V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C	-	5	100	nA
		V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-	5	100	nA

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; Fig. 12	-	4.5	5.6	mΩ
		V_{GS} = 7 V; I_D = 25 A; T_j = 25 °C; <u>Fig. 12</u>	-	5.1	7.9	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 100 °C; Fig. 13	-	7.3	8.7	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 175 °C; Fig. 13	-	10.3	12.3	mΩ
R _G	gate resistance	f = 1 MHz	-	0.9	-	Ω
Dynamic ch	aracteristics				'	
Q _{G(tot)}	total gate charge	I _D = 25 A; V _{DS} = 50 V; V _{GS} = 10 V; Fig. 14; Fig. 15	-	65.1	-	nC
		I _D = 0 A; V _{DS} = 0 V; V _{GS} = 10 V	-	32.2	-	nC
Q _{GS}	gate-source charge	I _D = 25 A; V _{DS} = 50 V; V _{GS} = 10 V; Fig. 14; Fig. 15	-	20.4	-	nC
Q _{GS(th)}	pre-threshold gate- source charge		-	12.5	-	nC
Q _{GS(th-pl)}	post-threshold gate- source charge		-	7.9	-	nC
Q_{GD}	gate-drain charge		-	13.5	-	nC
V _{GS(pl)}	gate-source plateau voltage	I _D = 25 A; V _{DS} = 50 V; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	4.8	-	V
C _{iss}	input capacitance	V _{DS} = 50 V; V _{GS} = 0 V; f = 1 MHz;	-	4616	-	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 16</u>	-	805	-	pF
C _{rss}	reverse transfer capacitance		-	12	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 50 \text{ V}; R_L = 2 \Omega; V_{GS} = 10 \text{ V};$	-	17.4	-	ns
t _r	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C$	-	16.3	-	ns
t _{d(off)}	turn-off delay time		-	35.1	-	ns
t _f	fall time		-	19.7	-	ns
Source-drai	n diode					1
V _{SD}	source-drain voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}; Fig. 17$	-	0.8	1.2	V
t _{rr}	reverse recovery time	$I_S = 25 \text{ A}$; $dI_S/dt = -100 \text{ A/}\mu\text{s}$; $V_{GS} = 0 \text{ V}$;	-	51.4	-	ns
Q _r	recovered charge	V _{DS} = 50 V; <u>Fig. 18</u>	-	67.3	-	nC
		1				

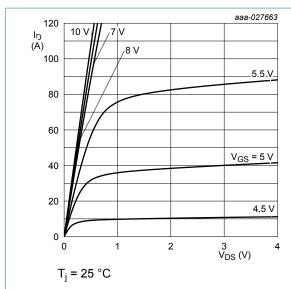


Fig. 8. Output characteristics; drain current as a function of drain-source voltage; typical values

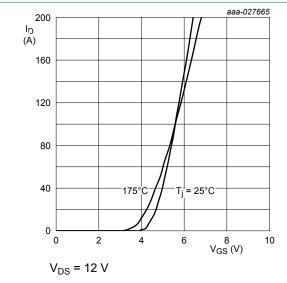


Fig. 10. Transfer characteristics; drain current as a function of gate-source voltage; typical values

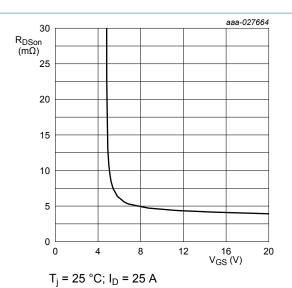


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

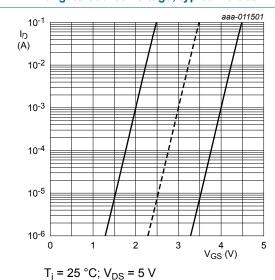


Fig. 11. Sub-threshold drain current as a function of

gate-source voltage

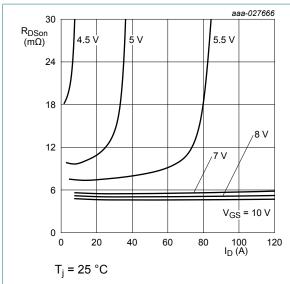


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

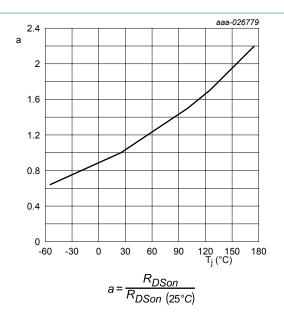


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

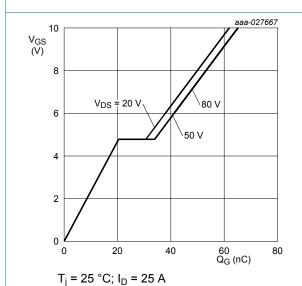


Fig. 14. Gate-source voltage as a function of gate charge; typical values

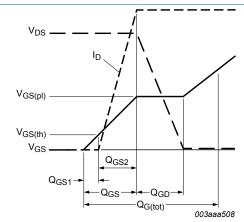


Fig. 15. Gate charge waveform definitions

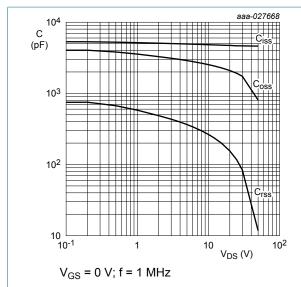
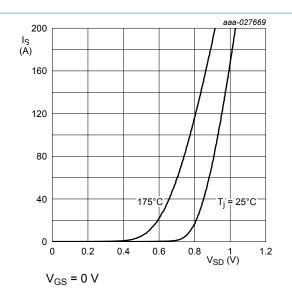


Fig. 16. Input, output and reverse transfer capacitances | Fig. 17. Source-drain (diode forward) current as a as a function of drain-source voltage; typical values



function of source-drain (diode forward) voltage; typical values

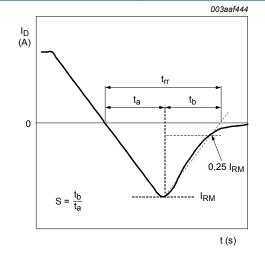


Fig. 18. Reverse recovery timing definition

11. Package outline

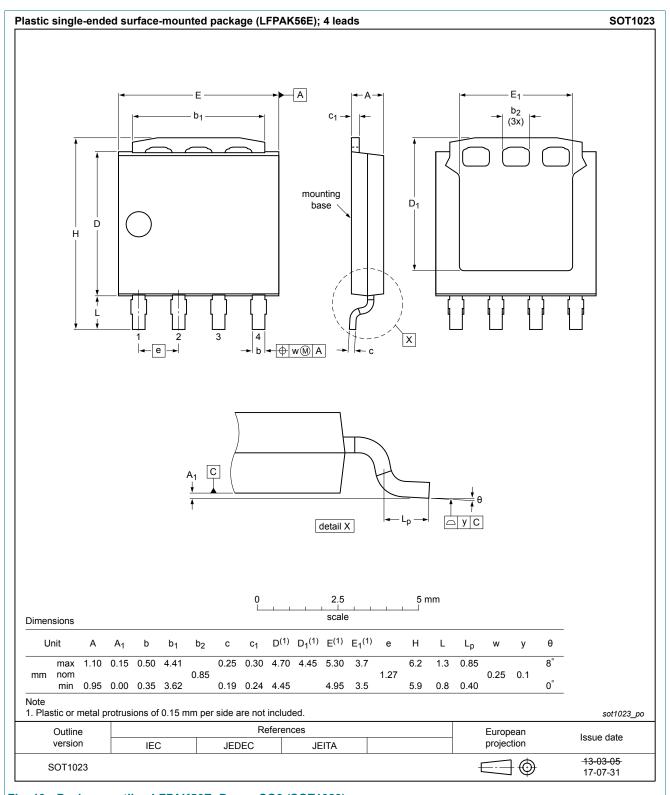
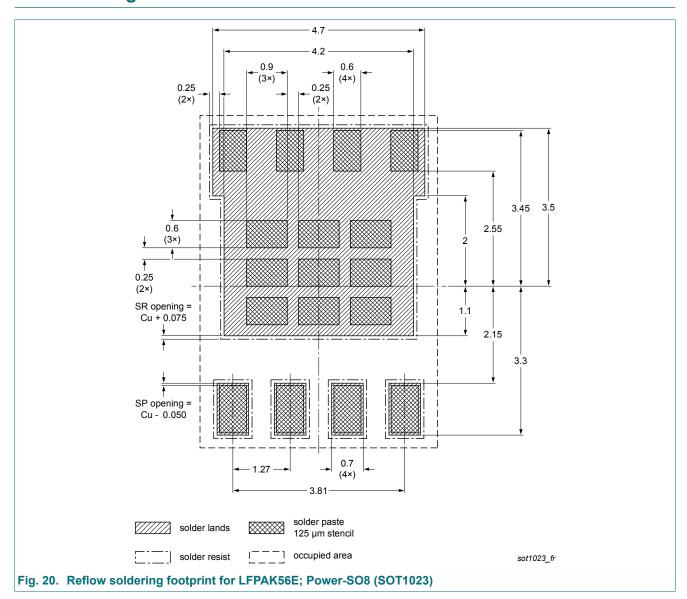


Fig. 19. Package outline LFPAK56E; Power-SO8 (SOT1023)

12. Soldering



13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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